## 2SD1895

## Silicon NPN triple diffusion planar type darlington

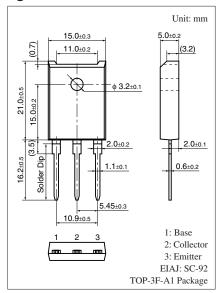
For power amplification Complementary to 2SB1255

#### ■ Features

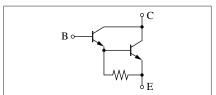
- Optimum for 60 W HiFi output
- High forward current transfer ratio hFE
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Full-pack package which can be installed to the heat sink with one screw

#### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Em	$V_{CBO}$	160	V	
Collector-emitter voltage (Base open)		$V_{CEO}$	140	V
Emitter-base voltage (Colle	$V_{EBO}$	5	V	
Collector current	$I_{C}$	8	A	
Peak collector current	$I_{CP}$	15	A	
Collector power dissipation		$P_{C}$	100	W
	$T_a = 25^{\circ}C$		3	
Junction temperature		$T_{j}$	150	°C
Storage temperature		$T_{stg}$	-55 to +150	°C
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#### Internal Connection



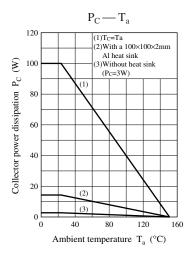
### ■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

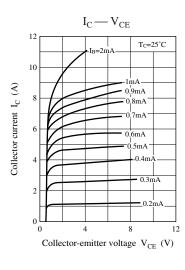
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	140			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 160 \text{ V}, I_E = 0$			100	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 140 \text{ V}, I_{B} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 5 \text{ V}, I_{C} = 0$			100	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	2000			_
	h <sub>FE2</sub> *	$V_{CE} = 5 \text{ V}, I_{C} = 7 \text{ A}$	5 000		30 000	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 7 \text{ A}, I_B = 7 \text{ mA}$			2.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 7 \text{ A}, I_B = 7 \text{ mA}$			3.0	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time	t <sub>on</sub>	$I_C = 7 \text{ A}, I_{B1} = 7 \text{ mA}, I_{B2} = -7 \text{ mA}$		2.0		μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		6.0		μs
Fall time	t <sub>f</sub>			1.2		μs

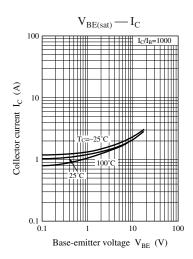
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

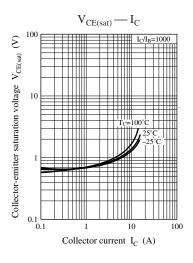
#### 2. \*: Rank classification

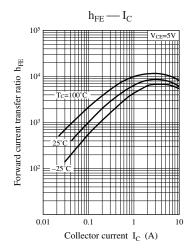
Rank	Q	Р		
h <sub>FE2</sub>	5 000 to 15 000	8 000 to 30 000		

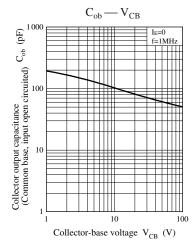


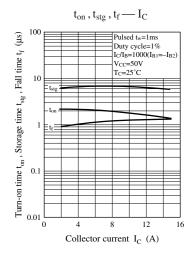


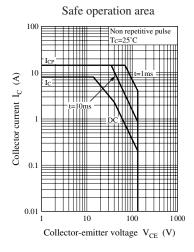




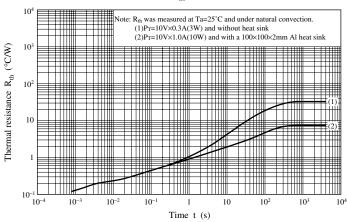












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